



Final Product Change Notification

201507008F01

Issue Date: 11-Jul-2015
Effective Date: 23-Oct-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Management Summary

Transfer the assembly production of BYV34G-600 (SOT226) from APP2 to NXP subcon Huashan in China. It is for better operation and capacity management.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Transfer the assembly production of BYV34G-600 from APP2 to NXP subcon Huashan

Details of this Change

SOT226 has been qualified and released at Huashan for number of years for other product types. BYV34G-600 is the only type of this package still being made at APP2. To achieve a better operation and capacity management, Bipolar PL decided to transfer it to Huashan.

The BOM and POD will use Huashan current BOM and POD so that to align with our other existing product types under the same package. The major different of BOM from APP2 to Huashan is the LF and Mould Compound. The LF will change from Ni-plated Cu to Bare Cu; and the Mould compound will change from Non-HF to HF. Those changes will not affect device performance or function. For the details, please refer to the attached qual report.

Why do we Implement this Change

It is for better operation and capacity management to support customer demand. The electrical performance, quality and reliability of this product remain the same.

Identification of Affected Products

Top side marking

The assembly code on the device marking will change from "m" to "A".

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 09-Oct-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 10-Aug-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.